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Power electronic packaging: design, assembly process, reliability and modeling

Yong, Liu, author

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Abstrak

Power electronic packaging presents an in-depth overview of power electronic packaging design, assembly,reliability and modeling. The book systematically introduces typical power electronic packaging design, assembly, reliability and failure analysis and material selection so readers can clearly understand each task's unique characteristics. This book also covers how advances in both semiconductor content and power advanced package design have helped cause advances in power device capability in recent years. The author extrapolates the most recent trends in the book's areas of focus to highlight where further improvement in materials and techniques can drive continued advancements, particularly in thermal management, usability, efficiency, reliability and overall cost of power semiconductor solutions.